



August 18, 2015

Rambus to Showcase New R+ DDR4 Server Memory Chipset at The 2015 Intel Developer Forum (IDF)

SAN FRANCISCO--(BUSINESS WIRE)-- Rambus, Inc. (NASDAQ:RMBS):

Who: Rambus, Inc. (NASDAQ: RMBS)

Where: IDF 2015
Moscone Convention Center
San Francisco, CA
Rambus Gold Sponsor booth #810 and DDR4 Memory Community booth #952

When: August 18 - 20, 2015

At the Intel Developer Form, Intel's premier event for developers and industry leaders, Rambus will demonstrate its R+ family of enhanced, JEDEC-compliant memory interface and serial link PHYs and chips designed to deliver advanced features and functionality. This will be the first public showcase of the newly announced R+ DDR4 Server DIMM chipset, RB26, which delivers superior performance and operating margin, along with advanced debug and serviceability. For additional details, visit www.rambus.com/dimmchipset.

Rambus Speaking Engagement:

Title: Future Challenges for DDR4 and Beyond in the Data Center and Enterprise Systems

Date: Wednesday, August 19, 2015

Time: 2:30PM - 3:30PM

Topic: Big data and escalating demands on IT are creating an explosion of data and real-time processing requirements that are fueling the need for increased memory speed and capacity across data centers and enterprise systems. As the industry evolves to meet these needs, there are key challenges in DDR4 memory design that must be addressed. This session will discuss the future fundamental challenges in DDR4 and post-DDR4 and critical design aspects, including signal integrity, channel characteristics and subsystem architecture that can enable systems to achieve maximum data rates and capacity cost-effectively.

Speaker: Ely Tsern, VP, Chief Technologist, Memory and Interfaces Division, Rambus Inc.

Location: Level 2, Room 2007

Follow Rambus

Company website: rambus.com

Rambus blog: rambusblog.com

Twitter: [@rambusinc](https://twitter.com/rambusinc)

LinkedIn: www.linkedin.com/company/rambus

Facebook: www.facebook.com/RambusInc

About Rambus Memory and Interfaces Division (MID)

The Rambus Memory and Interfaces Division develops products and services that solve the power, performance, and capacity challenges of the mobile, connected device, and cloud computing markets. Rambus enhanced standards-compatible and custom memory and serial link solutions include chips, architectures, memory and chip-to-chip interfaces, DRAM, IP validation tools, and system and IC design services. Developed through our system-aware design methodology, Rambus products deliver improved time-to-market and first-time-right quality.

About Rambus Inc.

Rambus creates cutting-edge semiconductor and IP products, spanning memory and interfaces to security, smart sensors and lighting. Our chips, customizable IP cores, architecture licenses, tools, services, training and innovations improve the

competitive advantage of our customers. We collaborate with the industry, partnering with leading ASIC and SoC designers, foundries, IP developers, EDA companies and validation labs. Our products are integrated into tens of billions of devices and systems, powering and securing diverse applications, including Big Data, Internet of Things (IoT), mobile, consumer and media platforms. At Rambus, we are makers of better. For more information, visit rambus.com.

RMBSTN

View source version on [businesswire.com](http://www.businesswire.com): <http://www.businesswire.com/news/home/20150818005431/en/>

For Rambus

Simone Souza, 408-462-8859

ssouza@rambus.com

or

From Racepoint Global

Hilary Costa, 415-694-6705

hcosta@racepointglobal.com

Source: Rambus, Inc.

News Provided by Acquire Media